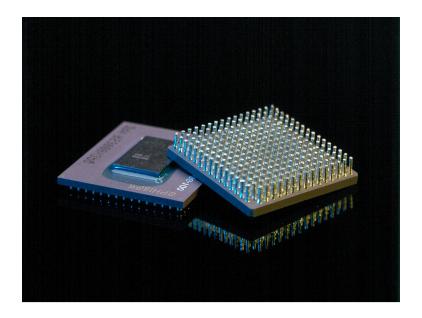


COLUMN ATTACH SERVICES

for Ruggedizing COTS Components



SIX SIGMA solder columns resolve solder joint reliability issues between Ceramic Ball Grid Array (CBGA) components and organic boards which are caused by Coefficient of Thermal Expansion (CTE) mismatch. SIX SIGMA uses unique columns composed of a copper ribbon wrapped around a high lead core. Each solder columns is mounted to the component using a precisely controlled volume of eutectic solder. Solder columns serve as a compliant interconnect thus reducing solder joint fatigue in extreme thermal cycle environments. Solder columns allow a board assembly to withstand significantly more temperature cycles than a similar assembly using solder balls.

SIX SIGMA is an AS9100:2009 & IS09001:2008 Quality Management Systems Registered Company and Full QML Q & V Certified Manufacturing facility.

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